	i	*					10.3
			•	•	<u> </u>		SHEET 1 OF
INFORM	IATION DISCLOS	URE CITA	TION	Atty Docket		Serial No.	, Ö
and NA	PTO-1449		-5-	65321 / 269250	4	Not Vet Assign 09/941 360	
				Applicant: Farhat et al.			9/941
Date Mailed:	August 28, 2001			Filing Date August 28, 2001		Group Art Unit	j10
		U.S	. PATENT	DOCUMENTS			
EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING DATE
100/	3959089	05/25/76	Watts		-		_
M/	4610772	09/09/86	Palnik				
MV.	5024735	06/18/91	Kadija				
m	6004880	12/21/99	Liu et al				
M_{λ}	3395092	07/30/68	Ribes				
M/	3436259	04/01/69	Regh et	al.		_	-
PAN/	3890746	06/24/75	Saegusa	et al.	—		
10Kn/	5863412	01/26/99	Ichinoise	e et al.			, ,
70,7	5755859	05/26/98	Brusic et	al.			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

EXAMINER

5807165

5930669

5933753

6004880

5171412

5429733

5558568

5650039

5692947

5833820

09/15/98

07/27/99

08/03/99

12/21/99

12/15/92

07/04/95

09/24/96

07/22/97

12-02-97

11/10/98

Uzoh et al.

Simon et al.

Talieh et al.

Talieh et al.

Talieh et al.

6

DATE CONSIDERED

Liu et al.

Ishida

Talieh

Dubin

Uzoh

SHEET 2 OF 2

INFORMATION DISCLOSURE CITATION PTO-1449				Atty Docket 65321 / 269250		Serial No. Not Yet Assigned							
				Applicant: Farhat et al.									
Date Mailed:	August 28, 2001		Filing Date August 28, 2001	Group Art Unit									
FOREIGN PATIENT DOCUMENTS													
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY CLA			SUBCLASS	Translation						
1784/	DE 2008664	09/09/71					Yes	No					
100/													
<i> </i>	DE 4324330	03/02/94	Germany										
M//	EP 0903774 A2	03/24/99	EP										
PU	EP 0960693 A2	12/01/99	EP										
01/	WO 95/00295	01/05/95	PCT										
	OTHER DOCU	VIENTS (Incl	uding Au	thor, Title, Date, Pertine	nt Page	s, Etc.)							
my	M. Rubinstein, "Tampongalvanisieren in de Praxis, Teil 2." GALVANOTECHNIK, Vol. 79, No. 10, 1988, pp. 3263-3270												
PRN	J.M. Steigerwald, R. Zirpoli, S.P. Murarka, D. Price and R.J. Gutman, "Pattern Geometry Effects in the Chemical-Mechanical Polishing of Inlaid Copper Structures", October 1994, pp. 2842-2848												
W	Alan C. West, Chin-Chang Cheng and Brett C. Baker, "Pulse Reverse Copper Electrodeposition in High Aspect Ratio Trenches and Vias", September 1998, pp070-3073												
M	Robert C. Contolini, Anthony F. Bernhardt and Steven Mayer, "Electrochemical Planarization for Multilevel Metallization", September 1994, pp. 2503-2510												
M	C. Madore, M. Matlosz and D. Landolt, "Blocking Inhibitors in Catholic Leveling", I. Theoretical Analysis", December 1996, pp. 3927-3942												
		^											
EXAMINER DONALD VALENTINE DATE CONSIDERED 6/03													

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance <u>and</u> not considered. Include copy of this form with next communication to applicant.